

HTC (High Thermal Conductivity) SILICONE

The product, **Heat Sink Compound**, was developed in response to the growing demand in microelectronics for increased thermal transfer efficiency. This product retains the normal properties of a standard Silicone Heat Sink Compound, but it has a thermal conductivity over 2 ½ times greater.

FEATURES:

- Off-White Paste color
- (-55 to 205)°C Operating Temperature Range
- 250 – 350 Consistency (Penetration, worked, 60x) ASTM D-217
- 0.00435 Thermal conductivity @36°C Cal/Sec.Cm°C Hot Wire Method
- 12.64 Thermal conductivity BTU.In/(Hr.Ft .F) per Mil-C047113B
- 1.82 Thermal conductivity W/m. °K
- 025°C Sq Inch/Watt Thermal Resistance @ 1 mil Film Thickness
- Electrically non-conductive grease; excellent dielectric properties
- 343 V/mil Dielectric strength, 0.05" gap, ASTM D-149
- 5.14 Dielectric constant, 25°C @ 1,000 Hz ASTM D-150
- 60 Months Shelf Life from D.o.M. (un-opened)

Product Availability:

| PART NO. | DESCRIPTION | SIZE | UPC: |
|--------------|----------------------|---------------|--------------|
| 10-8135 | Thermal HTC Silicone | 1 oz. Syringe | 010151134158 |
| 10-8135-0001 | Thermal HTC Silicone | 1 lb. Jar | 010151134394 |



CoO: USA
HTS: 8536.90.4000
ECCN: EAR99



PART No: **10-8135**